

# N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
100	0.110 at V <sub>GS</sub> = 10 V	15		
100	0.115 at V <sub>GS</sub> = 6 V	15		

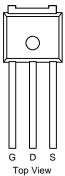
#### **FEATURES**

- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 %  $R_g$  Tested

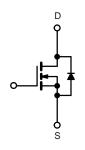
#### **APPLICATIONS**

• Primary Side Switch





TO-251



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_C$ =	25 °C, unless othe	rwise noted)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	L_	15		
	T <sub>C</sub> = 125 °C	D ID	8.7		
Pulsed Drain Current		I <sub>DM</sub>	45	А	
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>	15		
Avalanche Current	I <sub>AR</sub>	15			
Repetitive Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AR</sub>	11.3	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	Pn	61 <sup>b</sup>	w	
	T <sub>A</sub> = 25 °C	טי	2.7 <sup>a</sup>	vv	
Operating Junction and Storage Temperature Range	·	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
hunstien te Ambienti	t ≤ 10 s	R <sub>thJA</sub>	16	20	
Junction-to-Ambient <sup>a</sup>	Steady State		45	55	°C/W
Junction-to-Case		R <sub>thJC</sub>	2	2.4	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static		·					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	100			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0		3.0	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50		
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	15			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.110		Ω	
Drain-Source On-State Resistance <sup>b</sup>	P	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C		0.170			
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.230			
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A		0.115			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		25		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			892		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		110			
Reverse Transfer Capacitance	C <sub>rss</sub>			70			
Total Gate Charge <sup>c</sup>	Qg			20	25		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 75$ V, $V_{GS} = 10$ V, $I_{D} = 15$ A		5.5		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7			
Gate Resistance	Rg		1		3.2	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	12		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 75 \text{ V}, \text{ R}_{L} = 5 \Omega$		35	55	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 15 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{G}} = 2.5 \Omega$		17	25		
Fall Time <sup>c</sup>	t <sub>f</sub>	1		30	45		
Source-Drain Diode Ratings and Cha	racteristic (T	<sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				45	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_{F} = 15 \text{ A}, V_{GS} = 0 \text{ V}$		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 15 A, dl/dt = 100 A/μs		55	85	ns	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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55 °C

6

5

 $V_{GS} = 10 V$ 

20

25

T<sub>C</sub> = 125 °C

25 °C

3

4

2

10

16

**Gate Charge** 

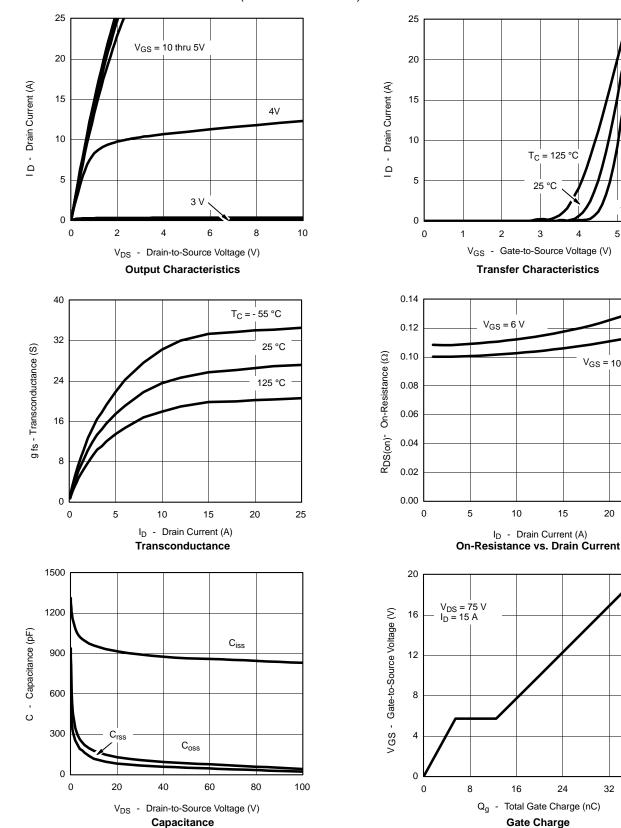
24

32

40

I<sub>D</sub> - Drain Current (A)

15

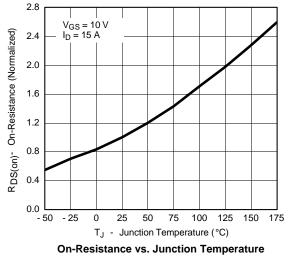


TYPICAL CHARACTERISTICS (25 °C unless noted)

服务热线:400-655-8788



#### TYPICAL CHARACTERISTICS (25 °C unless noted)



**THERMAL RATINGS** 

2

1

0.1

0.01

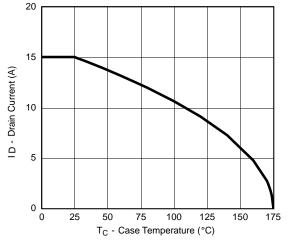
10-4

Normalized Effective Transient Thermal Impedance Duty Cycle = 0.5

0.02

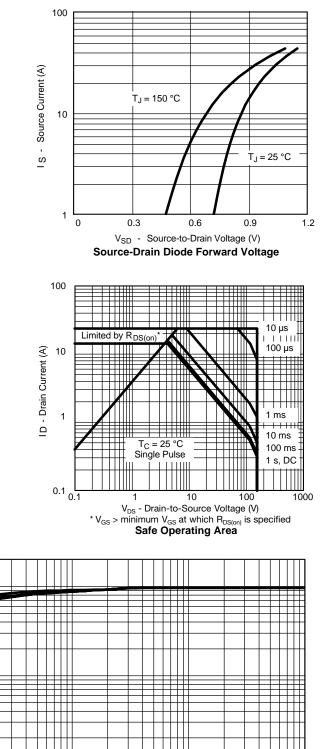
D.05 Single Pulse

0.2 0.1



Maximum Avalanche Drain Current vs. Case Temperature

10<sup>-3</sup>



1

Square Wave Pulse Duration (sec) Normalized Thermal Transient Impedance, Junction-to-Case

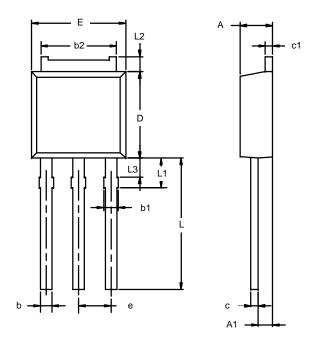
10<sup>-1</sup>

10-2

10



### TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

Min 2.21 0.89 0.71	Max 2.38	<b>Min</b> 0.087	<b>Max</b>	
0.89		0.087	0.004	
	1 14		0.094	
0.71	1.14	0.035	0.045	
	0.89	0.028	0.035	
0.76	1.14	0.030	0.045	
5.23	5.43	0.206	0.214	
0.46	0.58	0.018	0.023	
0.46	0.58	0.018	0.023	
5.97	6.22	0.235	0.245	
6.48	6.73	0.255	0.265	
2.28 BSC		0.090 BSC		
8.89	9.53	0.350	0.375	
1.91	2.28	0.075	0.090	
0.89	1.27	0.035	0.050	
1.15	1.52	0.045	0.060	
	5.23 0.46 0.46 5.97 6.48 2.26 8.89 1.91 0.89 1.15	5.23 5.43   0.46 0.58   0.46 0.58   5.97 6.22   6.48 6.73   2.28 BSC   8.89 9.53   1.91 2.28   0.89 1.27   1.15 1.52   46—Rev. E, 09-Jul-01	5.23     5.43     0.206       0.46     0.58     0.018       0.46     0.58     0.018       5.97     6.22     0.235       6.48     6.73     0.255       2.28 BSC     0.090       8.89     9.53     0.350       1.91     2.28     0.075       0.89     1.27     0.035       1.15     1.52     0.045	



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